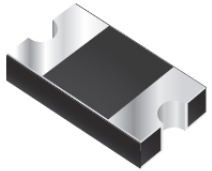


MATERIAL DECLARATION SHEET



Material Number	CD123D-B1xR			
Product Line	Semiconductor Products			
Compliance Date	2017/6/14			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	FRP	Others	7.50	Continuous filament glass fibers	65997-17-3	43	26.88	62.52%
				Copper foil	7440-50-8	14	8.75	
				Non-Hazardous cured resin	Proprietary	43	26.88	
2	Liquid Epoxy	Plastic	3.30	Silicon Dioxides	7631-86-9	55	15.14	27.53%
				Bis-phenol type liquid epoxy	9003-36-5	45	12.39	
3	Solder Paste	Metal	0.08	Lead *2	7439-92-1	88	0.62	0.70%
				Tin	7440-31-5	10	0.07	
				Silver	7440-22-4	2	0.01	
4	Dice	Others	0.87	Si	7440-21-3	97.98	7.11	7.25%
				Ti	7440-32-6	0.01	0.0007	
				Ni	7440-02-0	0.01	0.0007	
				Ag	7440-22-4	2	0.15	
5	Terminal Plating	Metal	0.24	Tin	7440-31-5	99.9	2.00	2.00%
				Others	-	0.1	0.002	
			Total weight	12.00				

MATERIAL DECLARATION SHEET



This Document was updated on: 2017/6/14

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. Excepted for RoHS 7(a)-Lead in high melting temperature type solders (i.e. lead- based alloys containing 85% by weight or more lead).